505074133 08/31/2018

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5120889

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MAKI ITO	08/28/2018
TOSHIAKI ISHII	08/27/2018
YOSHIO KAWAI	08/30/2018
NOBUTAKE TSUYUNO	08/27/2018
YUJIRO KANEKO	08/27/2018
TAKAYUKI FUKUZAWA	08/27/2018
MASAHIKO ASANO	08/30/2018

RECEIVING PARTY DATA

Name:	HITACHI AUTOMOTIVE SYSTEMS, LTD.
Street Address:	2520, TAKABA
City:	HITACHINAKA-SHI, IBARAKI
State/Country:	JAPAN
Postal Code:	312-8503

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16081515

CORRESPONDENCE DATA

Fax Number: (215)568-6499

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 215-568-6400

Email: Igivigliano@vklaw.com

Correspondent Name: VOLPE AND KOENIG, P.C.

Address Line 1: UNITED PLAZA

Address Line 2: 30 SOUTH 17TH STREET, 18TH FLOOR Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	HITACHI4-111502305US01
NAME OF SUBMITTER:	GERALD B. HALT, JR.
SIGNATURE:	/Gerald B. Halt, Jr./
DATE SIGNED:	08/31/2018

505074133 REEL: 046767 FRAME: 0415

Total Attachments: 6 source=HITACHI4_111502305US01_Assignment_EFS#page1.tif source=HITACHI4_111502305US01_Assignment_EFS#page2.tif source=HITACHI4_111502305US01_Assignment_EFS#page3.tif source=HITACHI4_111502305US01_Assignment_EFS#page4.tif source=HITACHI4_111502305US01_Assignment_EFS#page5.tif source=HITACHI4_111502305US01_Assignment_EFS#page6.tif

PATENT REEL: 046767 FRAME: 0416

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by HITACHI AUTOMOTIVE SYSTEMS, LTD.,

a corporation organized under the laws of Japan, located at

2520, Takaba, Hitachinaka-shi, Ibaraki, JAPAN

receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

RESIN-SEALED VEHICLE-MOUNTED CONTROL DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)		DATE SIGNED (署名日)
1) Maki Sto	Maki ITO	8/28/2018
2)	Toshiaki ISHII	
3)	Yoshio KAWAI	
4)	Nobutake TSUYUNO	**************************************
5)	Yujiro KANEKO	•
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7)	Masahiko ASANO	
8)		

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1)_	Maki ITO Toshiaki Oshi Toshiaki ISHII	8/27 /2018
2) ₋ 3) ₋	Yoshio KAWAI	
4)_ 5)_	Nobutake TSUYUNO Yujiro KANEKO	<u> </u>
6)_	Takayuki FUKUZAWA	
7)_ 8)_	Masahiko ASANO	

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INVENTOR(S)

(発明者フルネームサイン)	(署名日)
1) Maki ITO	
2) Toshiaki ISHII	
2) Toshiaki ISHII 3) Yoshio Kawai Yoshio KAWAI	8/30/2018
4) Nobutake TSUYUNO	
5) Yujiro KANEKO	
6) Takayuki FUKUZAWA	
7) Masahiko Asaho Masahiko ASANO	8/10/2012
8)	

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DATE SIGNED

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INIT (ENTOPIO)

(発明者フルネームサイン)		DATE SIGNED (署名日)	
1)	Maki ITO	·····	
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3)	Yoshio KAWAI		
4)	Nobutake TSUYUNO		
5)	yujiro Kaneko Yujiro KANEKO	8/27/2018	
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